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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	HCS08
Core Size	8-Bit
Speed	40MHz
Connectivity	I <sup>2</sup> C, SCI, SPI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	39
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x8/10b SAR
Oscillator Type	External, Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	48-QFN (7x7)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08gt8amfde">https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08gt8amfde</a>

Part Number	Package Description	Original (gold wire) package document number	Current (copper wire) package document number
MC68HC908JW32	48 QFN	98ARH99048A	98ASA00466D
MC9S08AC16			
MC9S908AC60			
MC9S08AC128			
MC9S08AW60			
MC9S08GB60A			
MC9S08GT16A			
MC9S08JM16			
MC9S08JM60			
MC9S08LL16			
MC9S08QE128			
MC9S08QE32			
MC9S08RG60			
MCF51CN128			
MC9RS08LA8	48 QFN	98ARL10606D	98ASA00466D
MC9S08GT16A	32 QFN	98ARH99035A	98ASA00473D
MC9S908QE32	32 QFN	98ARE10566D	98ASA00473D
MC9S908QE8	32 QFN	98ASA00071D	98ASA00736D
MC9S08JS16	24 QFN	98ARL10608D	98ASA00734D
MC9S08QB8			
MC9S08QG8	24 QFN	98ARL10605D	98ASA00474D
MC9S08SH8	24 QFN	98ARE10714D	98ASA00474D
MC9RS08KB12	24 QFN	98ASA00087D	98ASA00602D
MC9S08QG8	16 QFN	98ARE10614D	98ASA00671D
MC9RS08KB12	8 DFN	98ARL10557D	98ASA00672D
MC9S08QG8			
MC9RS08KA2	6 DFN	98ARL10602D	98ASA00735D



and this 1-kHz source are disabled. Power consumption is lower when the 1-kHz source is disabled, but in that case the real-time interrupt cannot wake the MCU from stop.

### 3.5.4 Active BDM Enabled in Stop Mode

Entry into the active background mode from run mode is enabled if the ENBDM bit in BDCSCR is set. This register is described in the [Chapter 15, “Development Support,”](#) section of this data sheet. If ENBDM is set when the CPU executes a STOP instruction, the system clocks to the background debug logic remain active when the MCU enters stop mode so background debug communication is still possible. In addition, the voltage regulator does not enter its low-power standby state but maintains full internal regulation. If the user attempts to enter either stop1 or stop2 with ENBDM set, the MCU will instead enter stop3.

Most background commands are not available in stop mode. The memory-access-with-status commands do not allow memory access, but they report an error indicating that the MCU is in either stop or wait mode. The BACKGROUND command can be used to wake the MCU from stop and enter active background mode if the ENBDM bit is set. After the device enters background debug mode, all background commands are available. The table below summarizes the behavior of the MCU in stop when entry into the background debug mode is enabled.

**Table 3-2. BDM Enabled Stop Mode Behavior**

Mode	PDC	PPDC	CPU, Digital Peripherals, FLASH	RAM	ICG	ATD	Regulator	I/O Pins	RTI
Stop3	Don't care	Don't care	Standby	Standby	Active	Disabled <sup>1</sup>	Active	States held	Optionally on

<sup>1</sup> Either ATD stop mode or power-down mode depending on the state of ATDPU.

### 3.5.5 LVD Enabled in Stop Mode

The LVD system is capable of generating either an interrupt or a reset when the supply voltage drops below the LVD voltage. If the LVD is enabled in stop by setting the LVDE and the LVDSE bits in SPMSC1 when the CPU executes a STOP instruction, then the voltage regulator remains active during stop mode. If the user attempts to enter either stop1 or stop2 with the LVD enabled for stop (LVDSE = 1), the MCU will instead enter stop3. The table below summarizes the behavior of the MCU in stop when the LVD is enabled.

**Table 3-3. LVD Enabled Stop Mode Behavior**

Mode	PDC	PPDC	CPU, Digital Peripherals, FLASH	RAM	ICG	ATD	Regulator	I/O Pins	RTI
Stop3	Don't care	Don't care	Standby	Standby	Standby	Disabled <sup>1</sup>	Active	States held	Optionally on

<sup>1</sup> Either ATD stop mode or power-down mode depending on the state of ATDPU.

## 5.7.1 Interrupt Pin Request Status and Control Register (IRQSC)

This direct page register includes two unimplemented bits which always read 0, four read/write bits, one read-only status bit, and one write-only bit. These bits are used to configure the IRQ function, report status, and acknowledge IRQ events.

	7	6	5	4	3	2	1	0
R	0	0	IRQEDG	IRQPE	IRQF	0	IRQIE	IRQMOD
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

**Figure 5-2. Interrupt Request Status and Control Register (IRQSC)**

**Table 5-2. IRQSC Field Descriptions**

Field	Description
5 IRQEDG	<b>Interrupt Request (IRQ) Edge Select</b> — This read/write control bit is used to select the polarity of edges or levels on the IRQ pin that cause IRQF to be set. The IRQMOD control bit determines whether the IRQ pin is sensitive to both edges and levels or only edges. When the IRQ pin is enabled as the IRQ input and is configured to detect rising edges, the optional pullup resistor is re-configured as an optional pulldown resistor. 0 IRQ is falling edge or falling edge/low-level sensitive. 1 IRQ is rising edge or rising edge/high-level sensitive.
4 IRQPE	<b>IRQ Pin Enable</b> — This read/write control bit enables the IRQ pin function. When this bit is set, the IRQ pin can be used as an interrupt request. Also, when this bit is set, either an internal pull-up or an internal pull-down resistor is enabled depending on the state of the IRQMOD bit. 0 IRQ pin function is disabled. 1 IRQ pin function is enabled.
3 IRQF	<b>IRQ Flag</b> — This read-only status bit indicates when an interrupt request event has occurred. 0 No IRQ request. 1 IRQ event detected.
2 IRQACK	<b>IRQ Acknowledge</b> — This write-only bit is used to acknowledge interrupt request events (write 1 to clear IRQF). Writing 0 has no meaning or effect. Reads always return 0. If edge-and-level detection is selected (IRQMOD = 1), IRQF cannot be cleared while the IRQ pin remains at its asserted level.
1 IRQIE	<b>IRQ Interrupt Enable</b> — This read/write control bit determines whether IRQ events generate a hardware interrupt request. 0 Hardware interrupt requests from IRQF disabled (use polling). 1 Hardware interrupt requested whenever IRQF = 1.
0 IRQMOD	<b>IRQ Detection Mode</b> — This read/write control bit selects either edge-only detection or edge-and-level detection. The IRQEDG control bit determines the polarity of edges and levels that are detected as interrupt request events. See <a href="#">Section 5.4.2.2, “Edge and Level Sensitivity”</a> for more details. 0 IRQ event on falling edges or rising edges only. 1 IRQ event on falling edges and low levels or on rising edges and high levels.

Refer to [Chapter 9, “Internal Clock Generator \(S08ICGV4\),”](#) for more information about using these pins as oscillator pins.

## 6.3 Parallel I/O Controls

Provided no on-chip peripheral is controlling a port pin, the pins operate as general-purpose I/O pins that are accessed and controlled by a data register (PTxD), a data direction register (PTxDD), a pullup enable register (PTxPE), and a slew rate control register (PTxSE) where x is A, B, C, D, E, or G.

Reads of the data register return the pin value (if PTxDDn = 0) or the contents of the port data register (if PTxDDn = 1). Writes to the port data register are latched into the port register whether the pin is controlled by an on-chip peripheral or the pin is configured as an input. If the corresponding pin is not controlled by a peripheral and is configured as an output, this level will be driven out the port pin.

### 6.3.1 Data Direction Control

The data direction control bits determine whether the pin output driver is enabled, and they control what is read for port data register reads. Each port pin has a data direction control bit. When PTxDDn = 0, the corresponding pin is an input and reads of PTxD return the pin value. When PTxDDn = 1, the corresponding pin is an output and reads of PTxD return the last value written to the port data register. When a peripheral module or system function is in control of a port pin, the data direction control still controls what is returned for reads of the port data register, even though the peripheral system has overriding control of the actual pin direction.

For the MC9S08GT16A/GT8A MCU, reads of PTG0/BKGD/MS will return the value on the output pin.

It is a good programming practice to write to the port data register before changing the direction of a port pin to become an output. This ensures that the pin will not be driven momentarily with an old data value that happened to be in the port data register.

### 6.3.2 Internal Pullup Control

An internal pullup device can be enabled for each port pin that is configured as an input (PTxDDn = 0). The pullup device is available for a peripheral module to use, provided the peripheral is enabled and is an input function as long as the PTxDDn = 0.

For the four configurable KBI module inputs on PTA7–PTA4, when a pin is configured to detect rising edges, the port pullup enable associated with the pin (PTAPEn) selects a pulldown rather than a pullup device.

### 6.3.3 Slew Rate Control

Slew rate control can be enabled for each port pin that is configured as an output (PTxDDn = 1) or if a peripheral module is enabled and its function is an output. Not all peripheral modules' outputs have slew rate control; refer to [Chapter 2, “Pins and Connections,”](#) for more information about which pins have slew rate control.

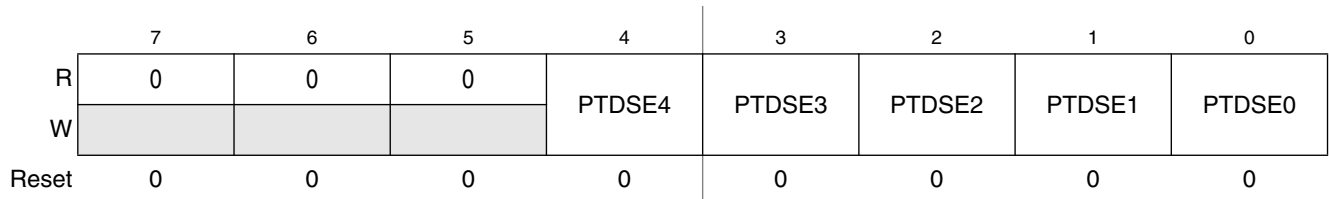


Figure 6-22. Slew Rate Control Enable for Port D (PTDSE)

Table 6-15. PTDSE Field Descriptions

Field	Description
4:0 PTDSE[4:0]	<p><b>Slew Rate Control Enable for Port D Bits</b> — For port D pins that are outputs, these read/write control bits determine whether the slew rate controlled outputs are enabled. For port D pins that are configured as inputs, these bits are ignored.</p> <p>0 Slew rate control disabled. 1 Slew rate control enabled.</p>

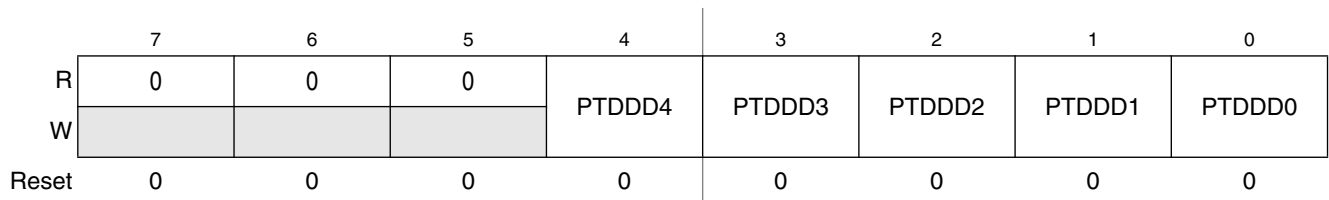


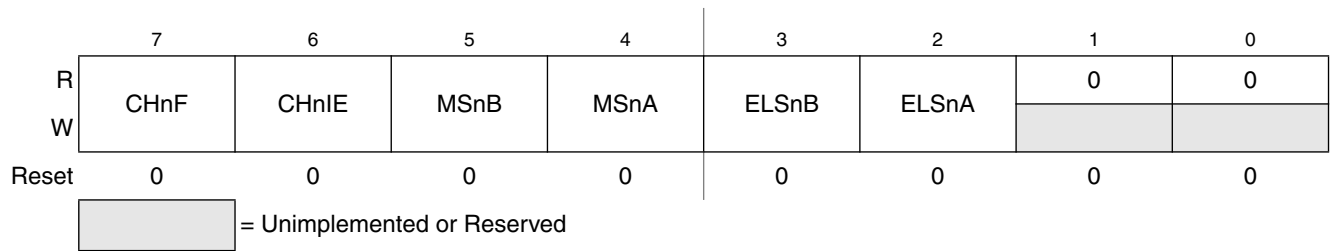
Figure 6-23. Data Direction for Port D (PTDDD)

Table 6-16. PTDDD Field Descriptions

Field	Description
4:0 PTDDD[4:0]	<p><b>Data Direction for Port D Bits</b> — These read/write bits control the direction of port D pins and what is read for PTDD reads.</p> <p>0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port D bit n and PTDD reads return the contents of PTDDn.</p>

### 10.3.4 Timer x Channel n Status and Control Register (TPMxCnSC)

TPMxCnSC contains the channel interrupt status flag and control bits that are used to configure the interrupt enable, channel configuration, and pin function.



**Figure 10-8. Timer x Channel n Status and Control Register (TPMxCnSC)**

**Table 10-4. TPMxCnSC Register Field Descriptions**

Field	Description
7 CHnF	<p><b>Channel n Flag</b> — When channel n is configured for input capture, this flag bit is set when an active edge occurs on the channel n pin. When channel n is an output compare or edge-aligned PWM channel, CHnF is set when the value in the TPM counter registers matches the value in the TPM channel n value registers. This flag is seldom used with center-aligned PWMs because it is set every time the counter matches the channel value register, which correspond to both edges of the active duty cycle period.</p> <p>A corresponding interrupt is requested when CHnF is set and interrupts are enabled (CHnIE = 1). Clear CHnF by reading TPMxCnSC while CHnF is set and then writing a 0 to CHnF. If another interrupt request occurs before the clearing sequence is complete, the sequence is reset so CHnF would remain set after the clear sequence was completed for the earlier CHnF. This is done so a CHnF interrupt request cannot be lost by clearing a previous CHnF. Reset clears CHnF. Writing a 1 to CHnF has no effect.</p> <p>0 No input capture or output compare event occurred on channel n 1 Input capture or output compare event occurred on channel n</p>
6 CHnIE	<p><b>Channel n Interrupt Enable</b> — This read/write bit enables interrupts from channel n. Reset clears CHnIE.</p> <p>0 Channel n interrupt requests disabled (use software polling) 1 Channel n interrupt requests enabled</p>
5 MSnB	<p><b>Mode Select B for TPM Channel n</b> — When CPWMS = 0, MSnB = 1 configures TPM channel n for edge-aligned PWM mode. For a summary of channel mode and setup controls, refer to <a href="#">Table 10-5</a>.</p>
4 MSnA	<p><b>Mode Select A for TPM Channel n</b> — When CPWMS = 0 and MSnB = 0, MSnA configures TPM channel n for input capture mode or output compare mode. Refer to <a href="#">Table 10-5</a> for a summary of channel mode and setup controls.</p>
3:2 ELSn[B:A]	<p><b>Edge/Level Select Bits</b> — Depending on the operating mode for the timer channel as set by CPWMS:MSnB:MSnA and shown in <a href="#">Table 10-5</a>, these bits select the polarity of the input edge that triggers an input capture event, select the level that will be driven in response to an output compare match, or select the polarity of the PWM output.</p> <p>Setting ELSnB:ELSnA to 0:0 configures the related timer pin as a general-purpose I/O pin unrelated to any timer channel functions. This function is typically used to temporarily disable an input capture channel or to make the timer pin available as a general-purpose I/O pin when the associated timer channel is set up as a software timer that does not require the use of a pin.</p>



transferred to the corresponding timer channel registers only after both 8-bit bytes of a 16-bit register have been written and the timer counter overflows (reverses direction from up-counting to down-counting at the end of the terminal count in the modulus register). This TPMxCNT overflow requirement only applies to PWM channels, not output compares.

Optionally, when TPMxCNTH:TPMxCNTL = TPMxMODH:TPMxMODL, the TPM can generate a TOF interrupt at the end of this count. The user can choose to reload any number of the PWM buffers, and they will all update simultaneously at the start of a new period.

Writing to TPMxSC cancels any values written to TPMxMODH and/or TPMxMODL and resets the coherency mechanism for the modulo registers. Writing to TPMxCnSC cancels any values written to the channel value registers and resets the coherency mechanism for TPMxCnVH:TPMxCnVL.

## 10.5 TPM Interrupts

The TPM generates an optional interrupt for the main counter overflow and an interrupt for each channel. The meaning of channel interrupts depends on the mode of operation for each channel. If the channel is configured for input capture, the interrupt flag is set each time the selected input capture edge is recognized. If the channel is configured for output compare or PWM modes, the interrupt flag is set each time the main timer counter matches the value in the 16-bit channel value register. See the [Resets, Interrupts, and System Configuration](#) chapter for absolute interrupt vector addresses, priority, and local interrupt mask control bits.

For each interrupt source in the TPM, a flag bit is set on recognition of the interrupt condition such as timer overflow, channel input capture, or output compare events. This flag may be read (polled) by software to verify that the action has occurred, or an associated enable bit (TOIE or CHnIE) can be set to enable hardware interrupt generation. While the interrupt enable bit is set, a static interrupt will be generated whenever the associated interrupt flag equals 1. It is the responsibility of user software to perform a sequence of steps to clear the interrupt flag before returning from the interrupt service routine.

### 10.5.1 Clearing Timer Interrupt Flags

TPM interrupt flags are cleared by a 2-step process that includes a read of the flag bit while it is set (1) followed by a write of 0 to the bit. If a new event is detected between these two steps, the sequence is reset and the interrupt flag remains set after the second step to avoid the possibility of missing the new event.

### 10.5.2 Timer Overflow Interrupt Description

The conditions that cause TOF to become set depend on the counting mode (up or up/down). In up-counting mode, the 16-bit timer counter counts from 0x0000 through 0xFFFF and overflows to 0x0000 on the next counting clock. TOF becomes set at the transition from 0xFFFF to 0x0000. When a modulus limit is set, TOF becomes set at the transition from the value set in the modulus register to 0x0000. When the counter is operating in up-/down-counting mode, the TOF flag gets set as the counter changes direction at the transition from the value set in the modulus register and the next lower count value. This corresponds to the end of a PWM period. (The 0x0000 count value corresponds to the center of a period.)

## 11.2.2 SCI Control Register 1 (SCIxC1)

This read/write register is used to control various optional features of the SCI system.

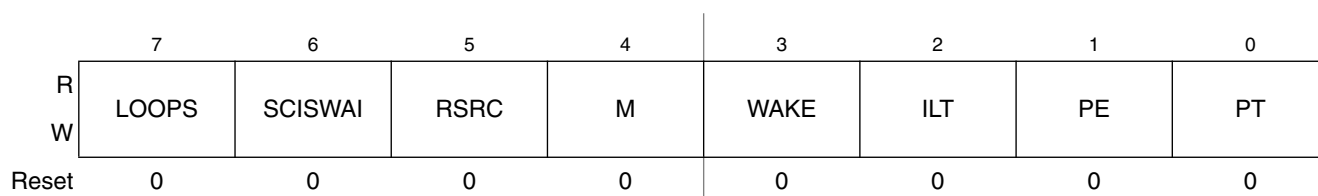


Figure 11-6. SCI Control Register 1 (SCIxC1)

Table 11-3. SCIxC1 Register Field Descriptions

Field	Description
7 LOOPS	<p><b>Loop Mode Select</b> — Selects between loop back modes and normal 2-pin full-duplex modes. When LOOPS = 1, the transmitter output is internally connected to the receiver input.</p> <p>0 Normal operation — RxD and TxD use separate pins.</p> <p>1 Loop mode or single-wire mode where transmitter outputs are internally connected to receiver input. (See <a href="#">RSRC</a> bit.) RxD pin is not used by SCI.</p>
6 SCISWAI	<p><b>SCI Stops in Wait Mode</b></p> <p>0 SCI clocks continue to run in wait mode so the SCI can be the source of an interrupt that wakes up the CPU.</p> <p>1 SCI clocks freeze while CPU is in wait mode.</p>
5 RSRC	<p><b>Receiver Source Select</b> — This bit has no meaning or effect unless the LOOPS bit is set to 1. When LOOPS = 1, the receiver input is internally connected to the TxD pin and RSRC determines whether this connection is also connected to the transmitter output.</p> <p>0 Provided LOOPS = 1, RSRC = 0 selects internal loop back mode and the SCI does not use the RxD pins.</p> <p>1 Single-wire SCI mode where the TxD pin is connected to the transmitter output and receiver input.</p>
4 M	<p><b>9-Bit or 8-Bit Mode Select</b></p> <p>0 Normal — start + 8 data bits (LSB first) + stop.</p> <p>1 Receiver and transmitter use 9-bit data characters start + 8 data bits (LSB first) + 9th data bit + stop.</p>
3 WAKE	<p><b>Receiver Wakeup Method Select</b> — Refer to <a href="#">Section 11.3.3.2, “Receiver Wakeup Operation”</a> for more information.</p> <p>0 Idle-line wakeup.</p> <p>1 Address-mark wakeup.</p>
2 ILT	<p><b>Idle Line Type Select</b> — Setting this bit to 1 ensures that the stop bit and logic 1 bits at the end of a character do not count toward the 10 or 11 bit times of the logic high level by the idle line detection logic. Refer to <a href="#">Section 11.3.3.2.1, “Idle-Line Wakeup”</a> for more information.</p> <p>0 Idle character bit count starts after start bit.</p> <p>1 Idle character bit count starts after stop bit.</p>
1 PE	<p><b>Parity Enable</b> — Enables hardware parity generation and checking. When parity is enabled, the most significant bit (MSB) of the data character (eighth or ninth data bit) is treated as the parity bit.</p> <p>0 No hardware parity generation or checking.</p> <p>1 Parity enabled.</p>
0 PT	<p><b>Parity Type</b> — Provided parity is enabled (PE = 1), this bit selects even or odd parity. Odd parity means the total number of 1s in the data character, including the parity bit, is odd. Even parity means the total number of 1s in the data character, including the parity bit, is even.</p> <p>0 Even parity.</p> <p>1 Odd parity.</p>

**Table 11-7. SCiXC3 Register Field Descriptions (continued)**

Field	Description
3 ORIE	<b>Overrun Interrupt Enable</b> — This bit enables the overrun flag (OR) to generate hardware interrupt requests. 0 OR interrupts disabled (use polling). 1 Hardware interrupt requested when OR = 1.
2 NEIE	<b>Noise Error Interrupt Enable</b> — This bit enables the noise flag (NF) to generate hardware interrupt requests. 0 NF interrupts disabled (use polling). 1 Hardware interrupt requested when NF = 1.
1 FEIE	<b>Framing Error Interrupt Enable</b> — This bit enables the framing error flag (FE) to generate hardware interrupt requests. 0 FE interrupts disabled (use polling). 1 Hardware interrupt requested when FE = 1.
0 PEIE	<b>Parity Error Interrupt Enable</b> — This bit enables the parity error flag (PF) to generate hardware interrupt requests. 0 PF interrupts disabled (use polling). 1 Hardware interrupt requested when PF = 1.

### 11.2.7 SCI Data Register (SCiXD)

This register is actually two separate registers. Reads return the contents of the read-only receive data buffer and writes go to the write-only transmit data buffer. Reads and writes of this register are also involved in the automatic flag clearing mechanisms for the SCI status flags.

	7	6	5	4	3	2	1	0
R	R7	R6	R5	R4	R3	R2	R1	R0
W	T7	T6	T5	T4	T3	T2	T1	T0
Reset	0	0	0	0	0	0	0	0

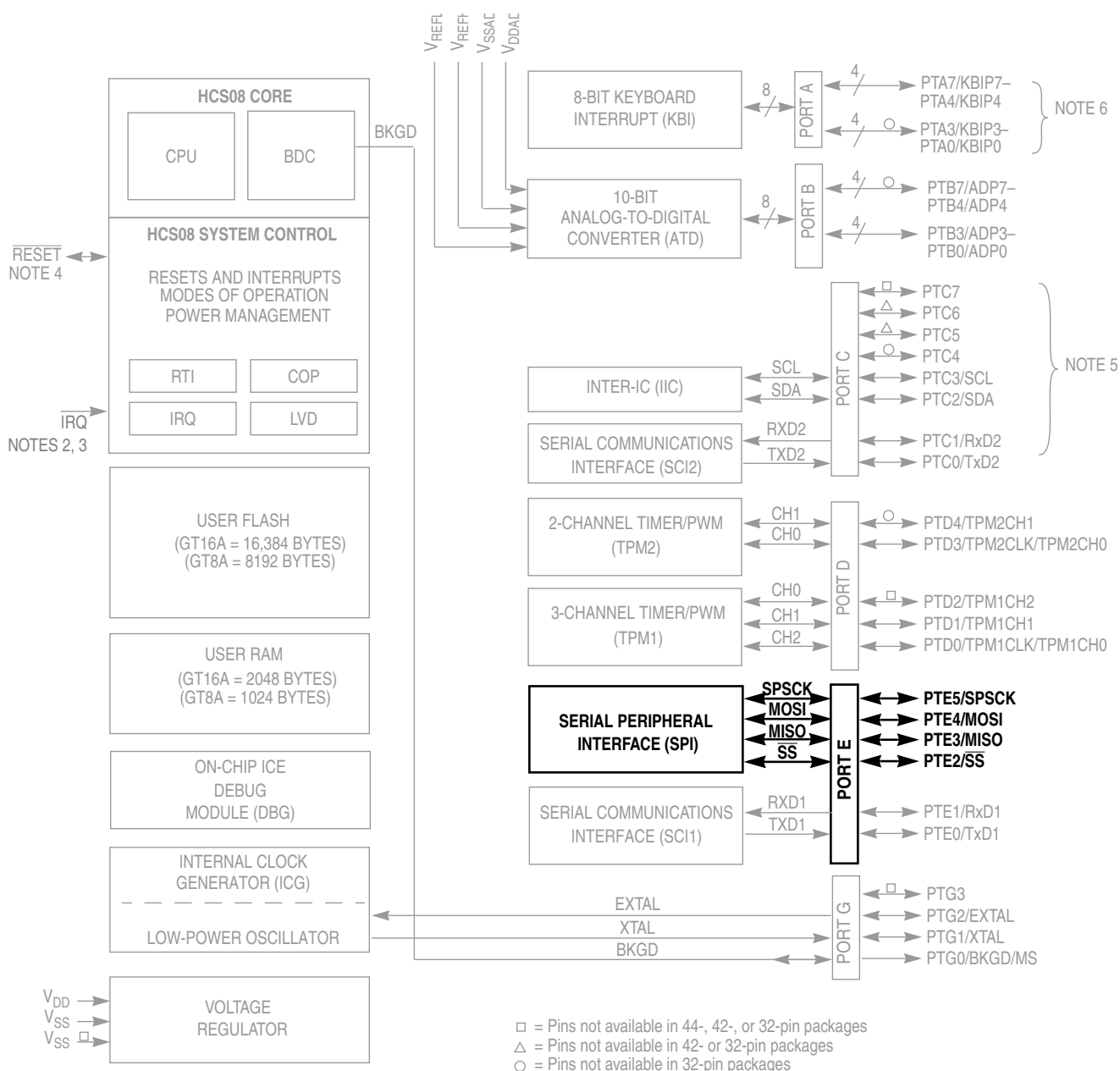
**Figure 11-11. SCI Data Register (SCiXD)**

## Chapter 12

# Serial Peripheral Interface (S08SPIV3)

### 12.1 Introduction

The MC9S08GT16A/GT8A provides one serial peripheral interface (SPI) module. The four pins associated with SPI functionality are shared with port E pins 2–5. See the [Appendix A, “Electrical Characteristics,”](#) appendix for SPI electrical parametric information. When the SPI is enabled, the direction of pins is controlled by module configuration. If the SPI is disabled, all four pins can be used as general-purpose I/O.



NOTES:

1. Port pins are software configurable with pullup device if input port.
2. Pin contains pullup/pulldown device if IRQ enabled (IRQPE = 1).
3. IRQ does not have a clamp diode to VDD. IRQ should not be driven above VDD.
4. Pin contains integrated pullup device.
5. High current drive
6. Pins PTA[7:4] contain both pullup and pulldown devices. Pulldown available when KBI enabled (KBIPn = 1).

Figure 12-1. Block Diagram Highlighting the SPI Module

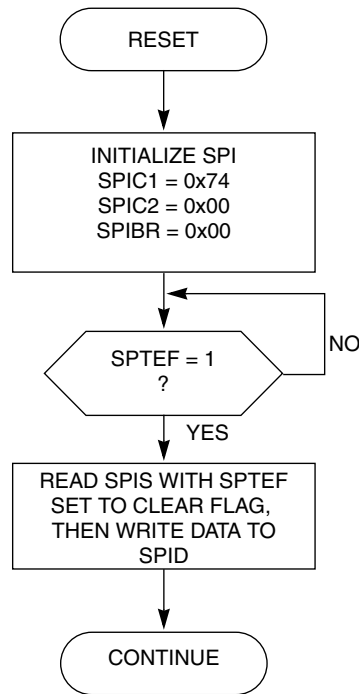


Figure 12-13. Initialization Flowchart Example for SPI Master Device

of how straight the line is (how far it deviates from a straight line). The adjusted ideal transition voltage is:

**Eqn. 14-6**

$$\text{Adjusted Ideal Trans. } V = \frac{(\text{Current Code} - 1/2)}{2^N} * ((V_{\text{REFH}} + E_{\text{FS}}) - (V_{\text{REFL}} + E_{\text{ZS}}))$$

- Zero scale error ( $E_{\text{ZS}}$ ) — This is the difference between the transition voltage to the first valid code and the ideal transition to that code. Normally, it is defined as the difference between the actual and ideal transition to code \$001, but in some cases the first transition may be to a higher code. The ideal transition to any code is:

**Eqn. 14-7**

$$\text{Ideal Transition } V = \frac{(\text{Current Code} - 1/2)}{2^N} * (V_{\text{REFH}} - V_{\text{REFL}})$$

- Full scale error ( $E_{\text{FS}}$ ) — This is the difference between the transition voltage to the last valid code and the ideal transition to that code. Normally, it is defined as the difference between the actual and ideal transition to code \$3FF, but in some cases the last transition may be to a lower code. The ideal transition to any code is:

**Eqn. 14-8**

$$\text{Ideal Transition } V = \frac{(\text{Current Code} - 1/2)}{2^N} * (V_{\text{REFH}} - V_{\text{REFL}})$$

- Total unadjusted error ( $E_{\text{TU}}$ ) — This is the difference between the transition voltage to a given code and the ideal straight-line transfer function. An alternate definition (with the same result) is the difference between the actual transfer function and the ideal straight-line transfer function. This measure of error includes inherent quantization error and all forms of circuit error (INL, DNL, zero-scale, and full-scale) except input leakage error, which is not due to the ATD.
- Input leakage error ( $E_{\text{IL}}$ ) — This is the error between the transition voltage to the current code and the ideal transition to that code that is the result of input leakage across the real portion of the impedance of the network that drives the analog input. This error is a system-observable error which is not inherent to the ATD, so it is not added to total error. This error is:

$$E_{\text{IL}} \text{ (in V)} = \text{input leakage} * R_{\text{AS}} \quad \text{Eqn. 14-9}$$

There are two other forms of error which are not specified which can also affect ATD accuracy. These are:

- Sampling error ( $E_{\text{S}}$ ) — The error due to inadequate time to charge the ATD circuitry
- Noise error ( $E_{\text{N}}$ ) — The error due to noise on  $V_{\text{AIN}}$ ,  $V_{\text{REFH}}$ , or  $V_{\text{REFL}}$  due to either direct coupling (noise source capacitively coupled directly on the signal) or power supply ( $V_{\text{DDAD}}$ ,  $V_{\text{SSAD}}$ ,  $V_{\text{DD}}$ , and  $V_{\text{SS}}$ ) noise interfering with the ATD's ability to resolve the input accurately. The error due to internal sources can be reduced (and specified operation achieved) by operating the ATD conversion in wait mode and ceasing all IO activity. Reducing the error due to external sources is dependent on system activity and board layout.

# Chapter 15

## Development Support

### 15.1 Introduction

Development support systems in the HCS08 include the background debug controller (BDC) and the on-chip debug module (DBG). The BDC provides a single-wire debug interface to the target MCU that provides a convenient interface for programming the on-chip FLASH and other nonvolatile memories. The BDC is also the primary debug interface for development and allows non-intrusive access to memory data and traditional debug features such as CPU register modify, breakpoints, and single instruction trace commands.

In the HCS08 Family, address and data bus signals are not available on external pins (not even in test modes). Debug is done through commands fed into the target MCU via the single-wire background debug interface. The debug module provides a means to selectively trigger and capture bus information so an external development system can reconstruct what happened inside the MCU on a cycle-by-cycle basis without having external access to the address and data signals.

The alternate BDC clock source for MC9S08GT16A/GT8A is the ICGCLK. See the [Chapter 9, “Internal Clock Generator \(S08ICGV4\),”](#) for more information about ICGCLK and how to select clock sources.



**A-Only** — Trigger when the address matches the value in comparator A

**A OR B** — Trigger when the address matches either the value in comparator A or the value in comparator B

**A Then B** — Trigger when the address matches the value in comparator B but only after the address for another cycle matched the value in comparator A. There can be any number of cycles after the A match and before the B match.

**A AND B Data (Full Mode)** — This is called a full mode because address, data, and R/W (optionally) must match within the same bus cycle to cause a trigger event. Comparator A checks address, the low byte of comparator B checks data, and R/W is checked against RWA if RWAEN = 1. The high-order half of comparator B is not used.

In full trigger modes it is not useful to specify a tag-type CPU breakpoint (BRKEN = TAG = 1), but if you do, the comparator B data match is ignored for the purpose of issuing the tag request to the CPU and the CPU breakpoint is issued when the comparator A address matches.

**A AND NOT B Data (Full Mode)** — Address must match comparator A, data must not match the low half of comparator B, and R/W must match RWA if RWAEN = 1. All three conditions must be met within the same bus cycle to cause a trigger.

In full trigger modes it is not useful to specify a tag-type CPU breakpoint (BRKEN = TAG = 1), but if you do, the comparator B data match is ignored for the purpose of issuing the tag request to the CPU and the CPU breakpoint is issued when the comparator A address matches.

**Event-Only B (Store Data)** — Trigger events occur each time the address matches the value in comparator B. Trigger events cause the data to be captured into the FIFO. The debug run ends when the FIFO becomes full.

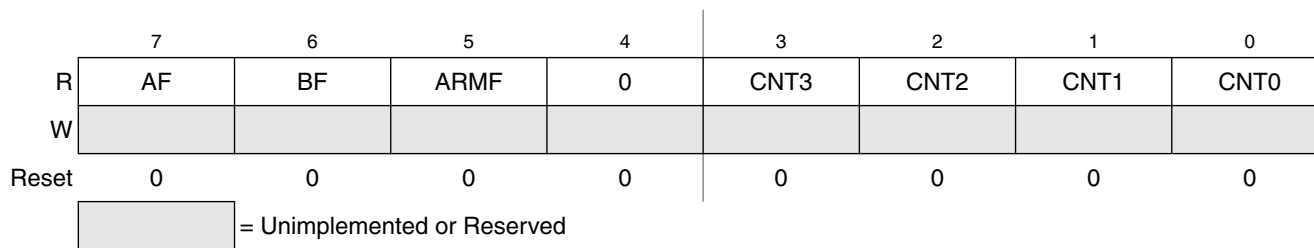
**A Then Event-Only B (Store Data)** — After the address has matched the value in comparator A, a trigger event occurs each time the address matches the value in comparator B. Trigger events cause the data to be captured into the FIFO. The debug run ends when the FIFO becomes full.

**Inside Range ( $A \leq \text{Address} \leq B$ )** — A trigger occurs when the address is greater than or equal to the value in comparator A and less than or equal to the value in comparator B at the same time.

**Outside Range ( $\text{Address} < A$  or  $\text{Address} > B$ )** — A trigger occurs when the address is either less than the value in comparator A or greater than the value in comparator B.

### 15.4.3.9 Debug Status Register (DBGS)

This is a read-only status register.



**Figure 15-9. Debug Status Register (DBGS)**

**Table 15-6. DBGS Register Field Descriptions**

Field	Description
7 AF	<b>Trigger Match A Flag</b> — AF is cleared at the start of a debug run and indicates whether a trigger match A condition was met since arming. 0 Comparator A has not matched 1 Comparator A match
6 BF	<b>Trigger Match B Flag</b> — BF is cleared at the start of a debug run and indicates whether a trigger match B condition was met since arming. 0 Comparator B has not matched 1 Comparator B match
5 ARMF	<b>Arm Flag</b> — While DBGEN = 1, this status bit is a read-only image of ARM in DBGIC. This bit is set by writing 1 to the ARM control bit in DBGIC (while DBGEN = 1) and is automatically cleared at the end of a debug run. A debug run is completed when the FIFO is full (begin trace) or when a trigger event is detected (end trace). A debug run can also be ended manually by writing 0 to ARM or DBGEN in DBGIC. 0 Debugger not armed 1 Debugger armed
3:0 CNT[3:0]	<b>FIFO Valid Count</b> — These bits are cleared at the start of a debug run and indicate the number of words of valid data in the FIFO at the end of a debug run. The value in CNT does not decrement as data is read out of the FIFO. The external debug host is responsible for keeping track of the count as information is read out of the FIFO. 0000 Number of valid words in FIFO = No valid data 0001 Number of valid words in FIFO = 1 0010 Number of valid words in FIFO = 2 0011 Number of valid words in FIFO = 3 0100 Number of valid words in FIFO = 4 0101 Number of valid words in FIFO = 5 0110 Number of valid words in FIFO = 6 0111 Number of valid words in FIFO = 7 1000 Number of valid words in FIFO = 8

**Table A-3. Thermal Characteristics**

Rating	Symbol	Value	Unit
Operating temperature range (packaged)	$T_A$	$T_L$ to $T_H$ -40 to 125	°C
Thermal resistance 1s board type			
48-pin QFN		84	
44-pin QFP	$\theta_{JA}^{1, 2}$	72	°C/W
42-pin SDIP		62	
32-pin QFN		99	
Thermal resistance 2s2p board type			
48-pin QFN		26	
44-pin QFP	$\theta_{JA}^{1,2}$	54	°C/W
42-pin SDIP		51	
32-pin QFN		33	

<sup>1</sup> Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, airflow, power dissipation of other components on the board, and board thermal resistance.

<sup>2</sup> Per SEMI G38-87 and JEDEC JESD51-2 with the single layer board horizontal. Single layer board is designed per JEDEC JESD51-3.

The average chip-junction temperature ( $T_J$ ) in °C can be obtained from:

$$T_J = T_A + (P_D \times \theta_{JA}) \quad \text{Eqn. A-1}$$

where:

$T_A$  = Ambient temperature, °C

$\theta_{JA}$  = Package thermal resistance, junction-to-ambient, °C/W

$P_D = P_{int} + P_{I/O}$

$P_{int} = I_{DD} \times V_{DD}$ , Watts — chip internal power

$P_{I/O}$  = Power dissipation on input and output pins — user determined

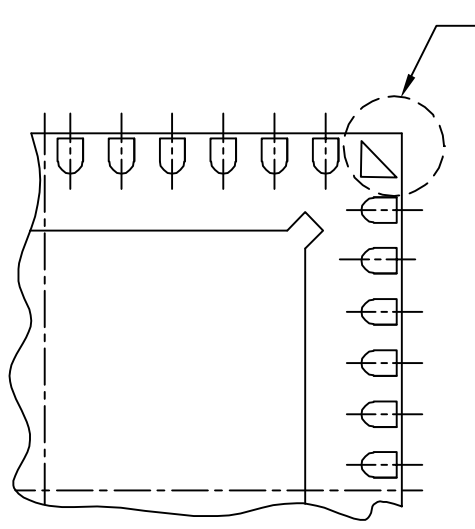
For most applications,  $P_{I/O} \ll P_{int}$  and can be neglected. An approximate relationship between  $P_D$  and  $T_J$  (if  $P_{I/O}$  is neglected) is:

$$P_D = K \div (T_J + 273^\circ\text{C}) \quad \text{Eqn. A-2}$$

Solving equations 1 and 2 for K gives:

$$K = P_D \times (T_A + 273^\circ\text{C}) + \theta_{JA} \times (P_D)^2 \quad \text{Eqn. A-3}$$

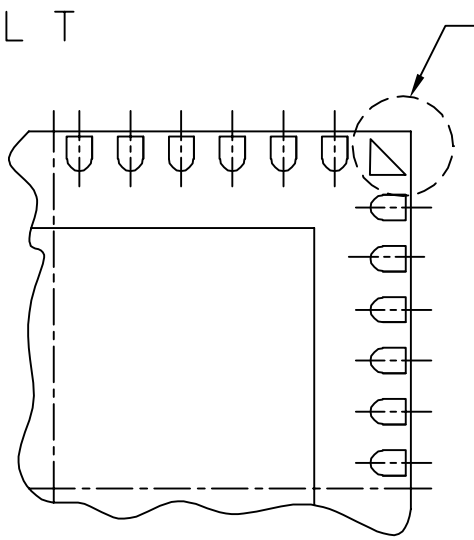
where K is a constant pertaining to the particular part. K can be determined from equation 3 by measuring  $P_D$  (at equilibrium) for a known  $T_A$ . Using this value of K, the values of  $P_D$  and  $T_J$  can be obtained by solving equations 1 and 2 iteratively for any value of  $T_A$ .



DETAIL T

DETAIL M

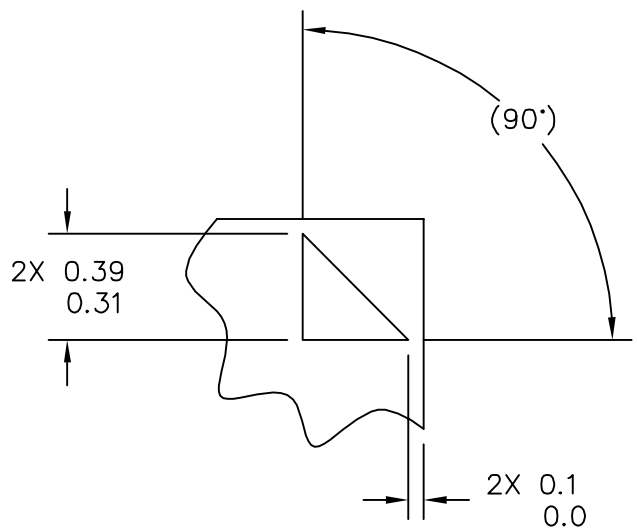
PIN 1 BACKSIDE IDENTIFIER OPTION



DETAIL T

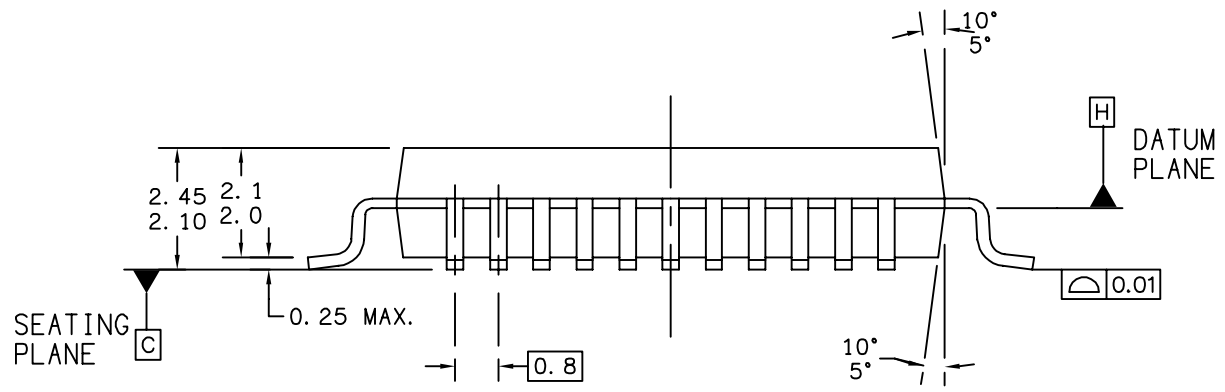
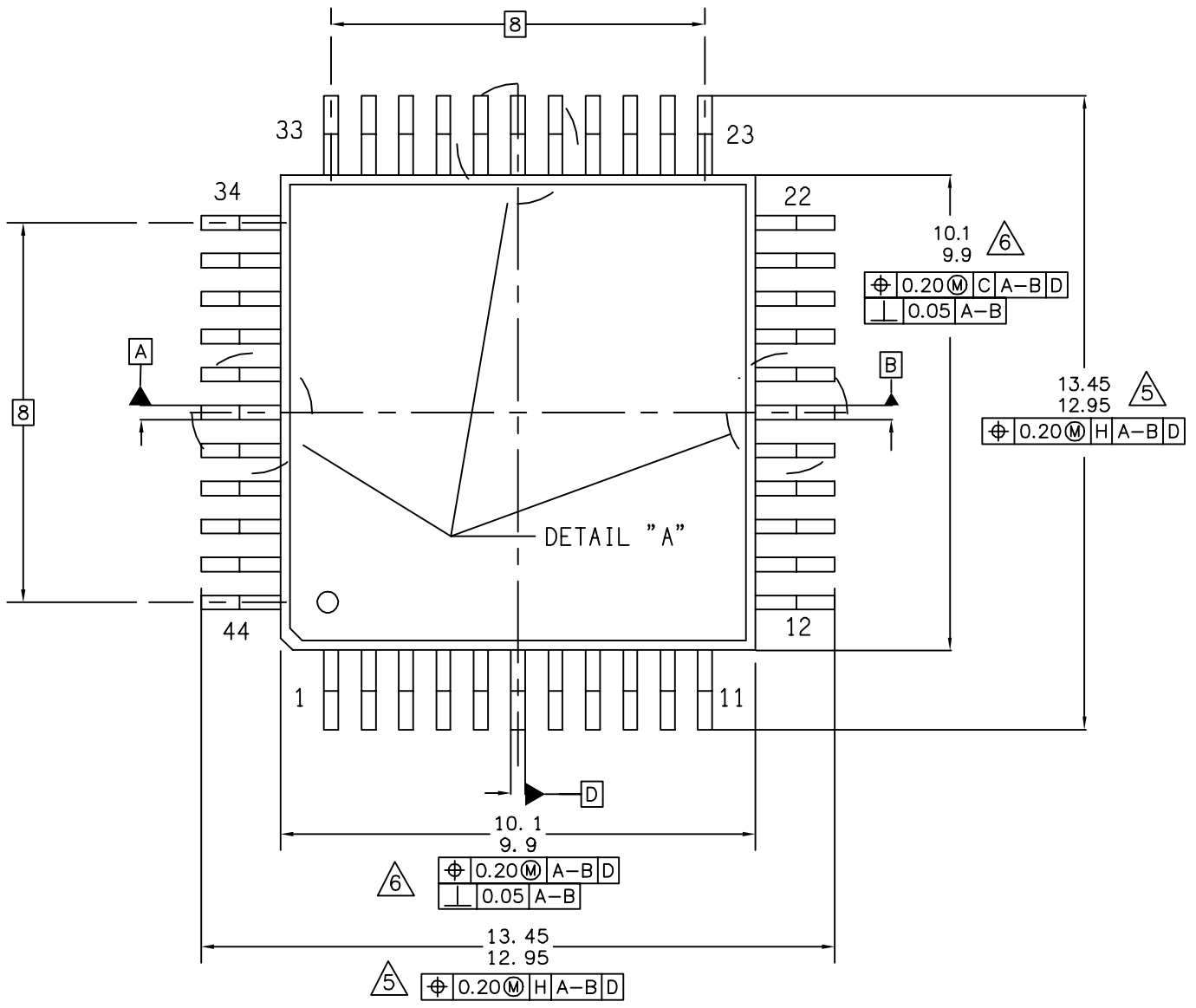
DETAIL M

PIN 1 BACKSIDE IDENTIFIER OPTION



DETAIL T

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	CASE NUMBER: 1314-05	05 DEC 2005	
	STANDARD: JEDEC-MO-220 VKKD-2		



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TITLE: 44LD QFP, 10X10X2.0 PKG, 0.8 PITCH	DOCUMENT NO: 98ASB42839B	REV: B	
	CASE NUMBER: 824A-01	06 APR 2005	
	STANDARD: NON-JEDEC		